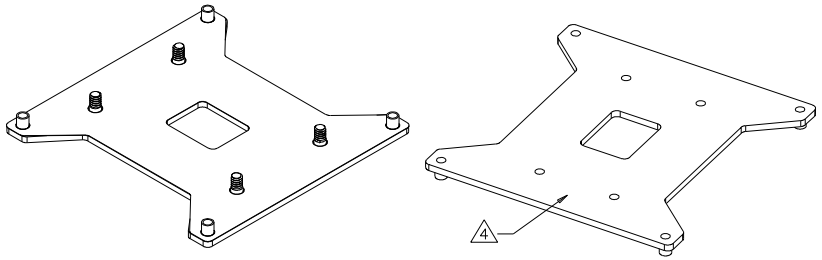
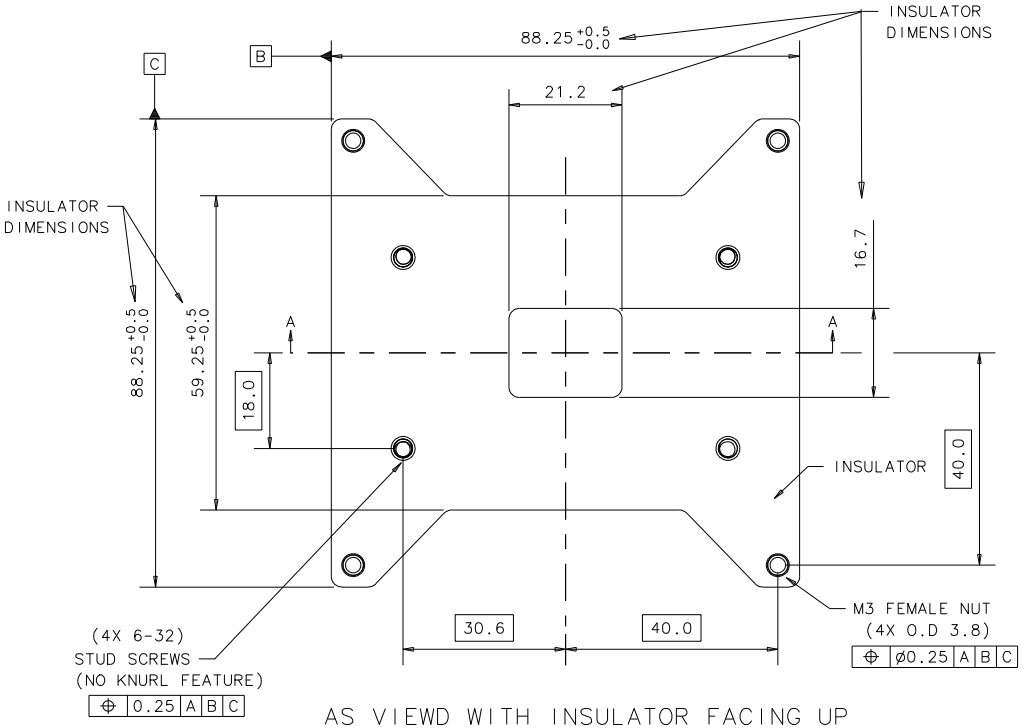
IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

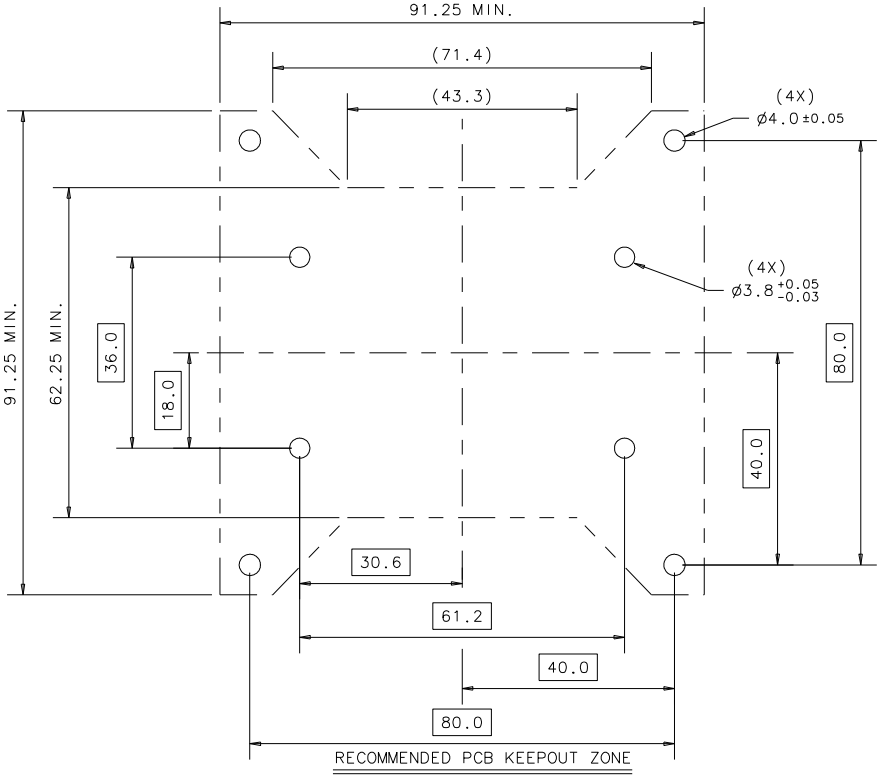
REV.	ECN. NO.	APPD.
A	BC100116556	N.LIN

NOTES:
1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MATERIAL : SERVER BACK PLATE — CARBON STEEL / THICKNESS 2.2MM
   PLATING ON BACK PLATE — 100u" MIN. NI PLATING OVERALL
   STUD SCREWS — STEEL WITH NI PLATING;
   FEMALE NUTS — STEEL
   INSULATOR — INSULATIVE MATERIAL / THICKNESS 0.178MM
4. "FOXCONN" "DATECODE" "13XXBPYR" ARE LOCATED APPROXMIATELY.
5. HARMFUL MATERIAL CONTROL PLEASE FOLLOW DOC. N.O. "EPI12".
6. PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.

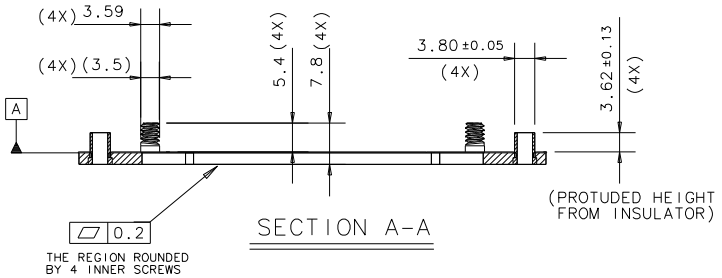




AS VIEWD WITH INSULATOR FACING UP



RECOMMENDED PCB KEEPOUT ZONE



SECTION A-A

X.±	X.°±	UNITS mm	NAME(INTENDED USE) LGA1366 SV BP
.X± 0.30	.X°±	MAT'L	
.XX± 0.25	.XX°±	FINISH	PART NO.(INTENDED USE) PT44P12-4104
.XXX±	.XXX°±	Q'TY	APPD: Nick Lin
			CHKD: Bill He
			DR: Tony su 10/14'10

THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF HON HAI PRECISION IND. CO., LTD. AND SHALL NOT BE REPRODUCED. COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF HON HAI PRECISION IND. CO., LTD.

FOXCONN
HON HAI PRECISION IND. CO.,LTD.
TAIPEI, TAIWAN, R.O.C.

TITLE: CUSTOMER DRAWING FOR LGA1366 SERVER BACK PLATE (NICKEL-PLATED)

DWG NO.: 351-0000-1149

SCALE	SHEET	REV.
1/1	1/1	A